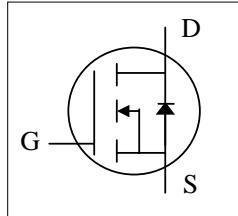
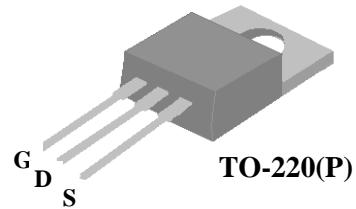




- ▼ Lower Gate Charge
- ▼ Simple Drive Requirement
- ▼ Fast Switching Characteristic
- ▼ RoHS Compliant & Halogen-Free



$BV_{DSS}$	40V
$R_{DS(ON)}$	20mΩ
$I_D$	32A



## Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220 package is widely preferred for commercial-industrial power applications and suited for low voltage applications such as DC/DC converters.

## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	32	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	20	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	120	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation	27.8	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Value	Units
$R_{thj-c}$	Maximum Thermal Resistance, Junction-case	4.5	°C/W
$R_{thj-a}$	Maximum Thermal Resistance, Junction-ambient	62	°C/W



# AP9962AGP-HF

## Electrical Characteristics @ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	40	-	-	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=20\text{A}$	-	-	20	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=16\text{A}$	-	-	30	$\text{m}\Omega$
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$	1	-	3	V
$\text{g}_{\text{fs}}$	Forward Transconductance	$\text{V}_{\text{DS}}=10\text{V}, \text{I}_D=20\text{A}$	-	40	-	S
$\text{I}_{\text{DSS}}$	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=40\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	10	$\mu\text{A}$
$\text{I}_{\text{GSS}}$	Gate-Source Leakage	$\text{V}_{\text{GS}}=\pm 20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
$\text{Q}_{\text{g}}$	Total Gate Charge <sup>2</sup>	$\text{I}_D=20\text{A}$	-	12	20	nC
$\text{Q}_{\text{gs}}$	Gate-Source Charge	$\text{V}_{\text{DS}}=32\text{V}$	-	2.7	-	nC
$\text{Q}_{\text{gd}}$	Gate-Drain ("Miller") Charge	$\text{V}_{\text{GS}}=4.5\text{V}$	-	7.8	-	nC
$t_{\text{d(on)}}$	Turn-on Delay Time <sup>2</sup>	$\text{V}_{\text{DS}}=20\text{V}$	-	7	-	ns
$t_r$	Rise Time	$\text{I}_D=20\text{A}$	-	46	-	ns
$t_{\text{d(off)}}$	Turn-off Delay Time	$\text{R}_G=3.3\Omega, \text{V}_{\text{GS}}=10\text{V}$	-	20	-	ns
$t_f$	Fall Time	$\text{R}_D=1.0\Omega$	-	6	-	ns
$C_{\text{iss}}$	Input Capacitance	$\text{V}_{\text{GS}}=0\text{V}$	-	820	1800	pF
$C_{\text{oss}}$	Output Capacitance	$\text{V}_{\text{DS}}=25\text{V}$	-	95	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance	f=1.0MHz	-	90	-	pF

## Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$\text{V}_{\text{SD}}$	Forward On Voltage <sup>2</sup>	$\text{I}_S=32\text{A}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1.2	V
$t_{\text{rr}}$	Reverse Recovery Time <sup>2</sup>	$\text{I}_S=10\text{A}, \text{V}_{\text{GS}}=0\text{V},$ $d\text{I}/dt=100\text{A}/\mu\text{s}$	-	19	-	ns
$\text{Q}_{\text{rr}}$	Reverse Recovery Charge		-	13	-	nC

## Notes:

1. Pulse width limited by Max. junction temperature.

2. Pulse test

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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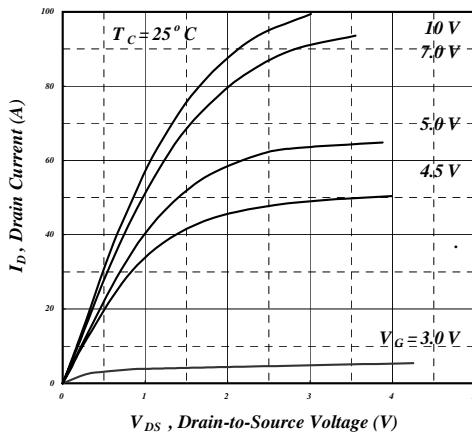


Fig 1. Typical Output Characteristics

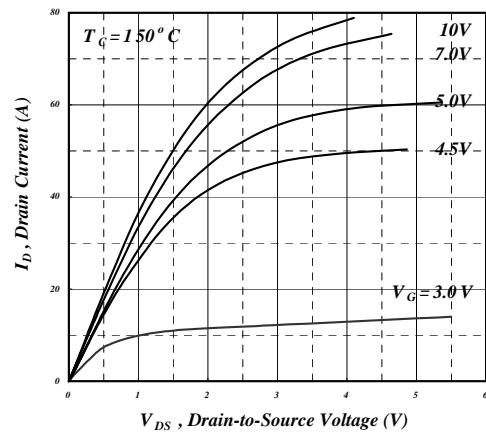


Fig 2. Typical Output Characteristics

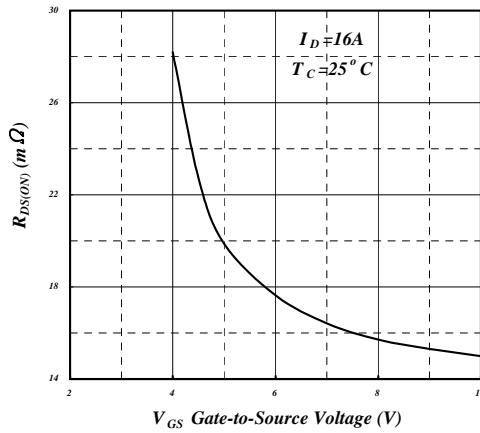


Fig 3. On-Resistance v.s. Gate Voltage

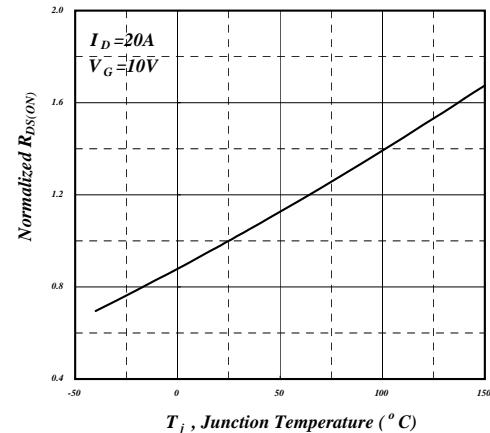


Fig 4. Normalized On-Resistance v.s. Junction Temperature

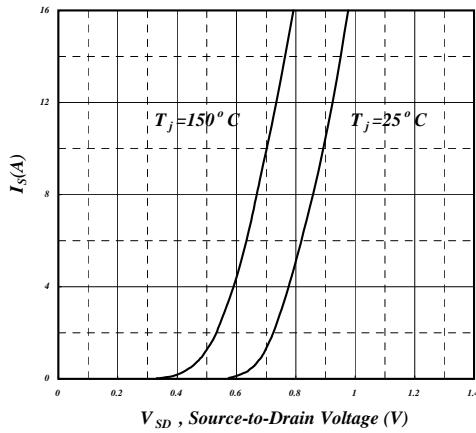


Fig 5. Forward Characteristic of Reverse Diode

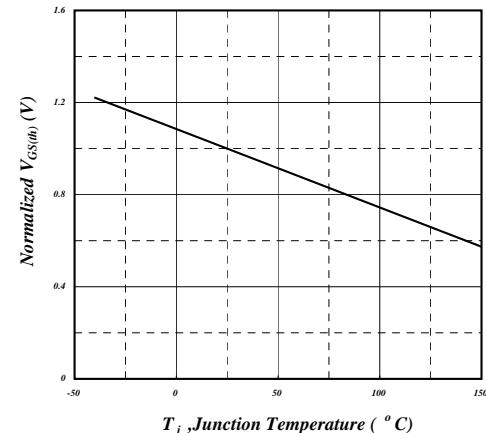


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

